



Product Change Notification: NTDO-09SMOR751

Date:

24-Jun-2026

Product Category:

HV Amplifier Arrays for MEMS and Piezo Drive

Notification Subject:

CCB 7313 Final Notice: Qualification of ATP7 as an additional assembly site for HV56020-V/KXX and HV56020T-V/KXX catalog part numbers available (CPN) in 43L VQFN (7x7x0.9mm) package.

Affected CPNs:

[NTDO-09SMOR751_Affected_CPN_06242026.pdf](#)

[NTDO-09SMOR751_Affected_CPN_06242026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for HV56020-V/KXX and HV56020T-V/KXX catalog part numbers available (CPN) in 43L VQFN (7x7x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Yes

Wire Material	Au	Au	Au	No
Die Attach Material	CRM-1085A	CRM-1085A	CRM-1085A	No
Molding Compound Material	G631BQF	G631BQF	G631BQF	No
Lead-Frame Material	C194	C194	C194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 26 July 2026 (date code: 2630)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2024					>	June 2026					July 2026			
Work Week	49	50	51	52	53		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date		X													
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date															X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 12, 2024: Issued initial notification.

June 24, 2026: Issued final notification. Added column "Change (Yes/No)" in the pre and post change

table. Attached the qualification report. Provided estimated first ship date to be on July 26, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_NTDO-09SMOR751_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

HV56020-V/KXX

HV56020T-V/KXX



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: NTDO-09SMOR751

Date:
June 16, 2026

**Qualification of ATP7 as an additional assembly site for
HV56020-V/KXX and HV56020T-V/KXX catalog part numbers
available (CPN) in 43L VQFN (7x7x0.9mm) package.**



MICROCHIP Package Qualification Report

Purpose: Qualification of ATP7 as an additional assembly site for HV56020-V/KXX and HV56020T-V/KXX catalog part numbers available (CPN) in 43L VQFN (7x7x0.9mm) package.

CCB No. 7313

<u>Misc.</u>	Assembly site	ANAC
	BD Number	BD-002813-01
	MP Code (MPC)	3500AQKXXA00
	Part Number (CPN)	HV56020T-V/KXX
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	3,000
<u>Lead-Frame</u>	Paddle size	210x222mils
	Material	C194
	DAP Surface Prep	Ag Plating
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes
	Part Number	101423810
	Lead Plating	MatteSn
<u>Bond Wire</u>	Strip Size	70x250
	Strip Density	240
<u>Die Attach</u>	Material	Au
	Part Number	CRM-1085A
<u>MC</u>	Conductive	Yes
	Part Number	G631BQF
<u>PKG</u>	PKG Type	VQFN
	Pin/Ball Count	43
	PKG width/size	7x7x0.9mm



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Package Qualification Report

Manufacturing Information:

Assembly Lot No
ATP7261500001.000
ATP7261500002.000
ATP7261500002.000

Conclusion:

Qualification of 3500A mask / 3500AQKXXA00 product / 1.0 mil Au wire in 43L VQFN 7x7x0.9mm package at ATP7 site is qualified for MSL3 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL3: 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2600165-1 ATP7261500001.000	R2600165-2 ATP7261500002.000	R2600165-3 ATP7261500003.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: ETS88_HV_BDG	25°C and 125°C		
Result:	Passed		



MICROCHIP Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 1 lot;		
Lot ID	R2600165-1 ATP7261500001.000	R2600165-2 ATP7261500002.000	R2600165-3 ATP7261500003.000
Electrical Results (Fail / Pass)	0/45	N/A	N/A
Electrical Test Tester: ETS88_HV_BDG	25°C and 125°C		
Result:	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP		
Lot ID	R2600165-1 ATP7261500001.000	R2600165-2 ATP7261500002.000	R2600165-3 ATP7261500003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/5	N/A	N/A
Electrical Test Tester: ETS88_HV_BDG	125°C		
Result:	Passed		



MICROCHIP Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600165-1 ATP7261500001.000	R2600165-2 ATP7261500002.000	R2600165-3 ATP7261500003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: ETS88_HV_BDG	25°C and 125°C		
Result:	Passed		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600165-1 ATP7261500001.000	R2600165-2 ATP7261500002.000	R2600165-3 ATP7261500003.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: ETS88_HV_BDG	25°C		
Result:	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 215°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 - Passed



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Package Qualification Report

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 - Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 - Passed

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 – Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - Passed

Bond Line Thickness

Test Method	SPI-45528
Test Criteria	0.60-1.50mils
Required Sample Size	5 units each lot / 3 lots
Result (Fail / Pass)	0/15 - Passed

Wire sweep

Test Method	X-ray
Test Criteria	15%
Required Sample Size	15 wires each lot / 3 lots
Result (Fail / Pass)	0/45 – Passed